



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: Tsuga et al.

Docket No.: TI-31619

Serial No.: 10/072,073

Art Unit: 1746

Filed: 02/08/02

Examiner: Kornakov, M.

Title: Method for Removing Particles on Semiconductor Wafers

AMENDMENT UNDER 37 CFR §1.312

February 2, 2005

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)

I hereby certify that the above correspondence is being deposited
with the U.S. Postal Service on 2-2-05
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Karen Vertz
Karen Vertz

2-2-05
Date

This application is in condition for allowance except for the correction of formal matters. In response to the telephone conversations between the Applicant's attorney and the Examiner, in the above-identified patent application, please make the following amendments. They are respectfully submitted as a full and complete response to The Examiner's requests. Charge any required fees to the deposit account of Texas Instruments Incorporated, Account No. 20-0668.